PATENT ABSTRACTS OF JAPAN

(11)Publication number:

07-045557

(43) Date of publication of application: 14.02.1995

(51)Int.Cl.

H01L 21/301 C09J 7/02

CO9J 7/02 CO9J 7/02

(21)Application number: 05-184704

(71)Applicant: LINTEC CORP

(22) Date of filing:

27.07.1993

(72)Inventor: KOMIYAMA MIKIO

SENOO HIDEO

HOSONO SHIGERU

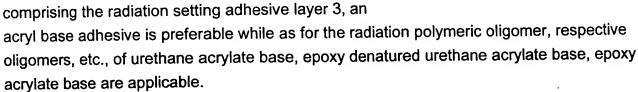
EBE KAZUYOSHI

(54) WAFER STICKING ADHESIVE SHEET

(57) Abstract:

PURPOSE: To avoid the deviation in chip bodies for enabling the pick up to be stably performed by a method wherein the modulus of elasticity after radiation setting of radiation setting adhesive layer comprising a bonding agent and radiation polymeric oligomer is to be specified.

CONSTITUTION: The title wafer sticking adhesive sheet 1 is formed by forming a radiation setting adhesive layer 3 on a base substance 2 further forming a die bonding agent layer 4 on the layer 3. The modulus of elasticity of the radiation setting adhesive layer 3 after the radiation setting step is specified to be 1×106[dynes/cm2]-1×108[dynes/cm2] comprising the radiation setting adhesive layer 3, an



LEGAL STATUS

[Date of request for examination]

24.03.2000

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2000 Japan Patent Office